



LAND



SEA



AIR

7SL-R760

INTEL 4/5TH XEON SP 2U, 2-SOCKET
AI/ML MILITARY RUGGED HPC



- Two Intel® 4th /5th Xeon Scalable Processor CPUs with up to 56/64 Cores
- 32 DDR5 DIMM slots, supports RDIMM 8 TB max, speeds up to 5600 MT/s. Supports registered ECC DDR5 DIMMs only
- Front bays: Up to 24 x 2.5-inch SATA III, SAS, or NVMe SSDs (HDD/SSD) max 368.64TB
- Cryptographically signed firmware, Secure Boot, TPM 2.0 FIPS, CC-TCG certified
- 2x 25G LAN SFP+, 10GbE LAN ,1x USB 3.0, 1x USB2.0,1x VGA
- Up to 8 PCIe slots (6 x16 Gen4/Gen5, 1 x 8 LPHL Gen4, 1 x 16 LPHL Gen4)
- Redundant 2400W Platinum power supply support 100V-240V, 240V HVDC support 1+1 active-active support hot plug
- Embedded Management: iDRAG Direct, iDRAC RESTful API with Redfish iDRAC Service
- Lightweight aluminum chassis with stainless steel reinforcement
- Electrical interference input filtering and cable shielding
- Conformal coating (Options)
- Design to meet MIL-STD-461/MIL-STD-810
- Optional Direct Liquid Cooling (DLC) or Conduction Liquid Cooling Plate (CLCP)

Product Highlight

Technical Specification

5th/4th Gen Intel® Xeon® Scalable processors, Two Socket LGA-4677 (Socket E)

Up to 56/64 Cores per Processor

Up to 8TB memory with 32 DIMM slots

Storage Internal Controllers: PERC H965i, PERC H965e, PERC H755, PERC H355, HBA355i

(BOSS-N1): HWRAID 1, 2 x M.2 NVMe SSDs

Management and Operating System

Windows®, VMWARE, Ubuntu Server LTS, Windows Server with Hyper-V, Red Hat Enterprise Linux, SUSE Linux Enterprise Server, VMware ESX

AMI UEFI BIOS type

iDRAC9, iDRAC Direct, iDRAC RESTful API with Redfish, iDRAC Service Module, NativeEdge Endpoint Orchestrator TPM 2.0 support

Expansion

Up to 8 PCIe slots (6 x16 Gen4/Gen5, 1 x 8 LP Gen4, 1 x 16 LP Gen4)

24x 2.5-inch SATA III, SAS, or NVMe SSDs max 368.64 TB

Input/Output Versatility

1x Power Button

1x SSD Status LED

2x AC-IN Jack

(Front)

1x iDRAC Direct (Micro-AB USB 2.0) port, 1 x USB 2.0

(Rear)

1 x iDRAC dedicated port, 1 x USB 3.0, 1 x Serial (Micro- AB USB 2.0) port, 1 x Mini-DisplayPort or VGA, 2 x 10GbE LAN, 2 x 25 GbE SFP+ LOM

Power Supply Options

Redundant 2400 W Platinum 100/240V VAC

1100 W 48 V~ (60) VDC (Optional)

Thermal Solution

Air Cooling 6 x Standard cold fans

Optional Direct Liquid Cooling (DLC) or Conduction Liquid Cooling Plate (CLCP)

Environmental

Operating

Temperature: -10°C to 55°C

Humidity: 5%to 95%, non-condensing

Shock: 3 axis, 25g

Vibration: 5Grms

Non-Operating

Temperature: -20°C to 60°C

Humidity: 5%to 95%, non-condensing

MIL-STD-810 Test

Method 500.5, Procedures I and II (Altitude, Operation): 12,192M, (40,000 ft) for the initial cabin altitude (18.8Kpa or 2.73 Psia)

Method 500.5, Procedures III and IV (Altitude, Non-Operation):

15,240, (50,000 ft) for the initial cabin altitude (14.9Kpa or 2.16 Psia)

Method 501.5, Procedure I (Storage/High Temperature)

Method 501.5, Procedure II (Operation/High Temperature)

Method 502.5, Procedure I (Storage/Low Temperature)

Method 502.5, Procedure II (Operation/Low Temperature)

Method 503.5, Procedure I (Temperature shock)

Method 507.5, Procedure II (Temperature & Humidity)

Method 509.7 Salt Spray (50±5)g/L(Optional for Conformal Coating)

Method 514.6, Vibration Category 24/Non-Operating (Category 20 & 24, Vibration)

Method 514.6, Vibration Category 20/Operating (Category 20 & 24, Vibration)

Method 516.6, Shock-Procedure V Non-Operating (Mechanical Shock)

Method 516.6, Shock-Procedure I Operating (Mechanical Shock)

Mechanical

Height: 3.41 inches (86.8mm)

Width: 19 inches (482.6mm)

Depth: 22 inches (572mm) with bezel

18.57inches (471.8mm) without bezel

Weight: 46.64 pounds (21.16kg)

Specifications

SYSTEM

Processor	Two 5th Gen Intel® Xeon® / 4th Gen Intel® Xeon® Scalable processors, Socket E (LGA-4677)
CPU Core Count	Up to 56Cores/64Cores
Memory type	DDR5-5600MT/s RDIMM ECC, up to 8TB in 32 DIMM slots
GPU Options	Up to 5 x 75W (Single Width Full Height/Half Length, Low Profile) GPU or Up to 2 x 300W (Double Width Full Height/Full Length)
TPM	Chipset: Infineon, Type: TPM 2.0
IPMI	iDRAC RESTful API with Redfish
BIOS	AMI UEFI BIOS
USB	1x USB3.0 +1x USB2.0 ports
Ethernet	2x 25G Ethernet SFP+ Ports
Power Type	100V~240V AC IN Redundant
Storage	24x 2.5" Swappable SATA SAS, or NVMe (HDD/SSD)
Operating Temp.	-10°C to +55°C
Dimension	482mm(W) x 572mm(D)x86mm(H)

FRONT I/O

Power Button	1x
SSD LED indicator	1x
Swappable SSD Tray	24x
iDRAC	1x iDRAC Direct (Micro-AB USB 2.0) port, 1 x USB 2.0

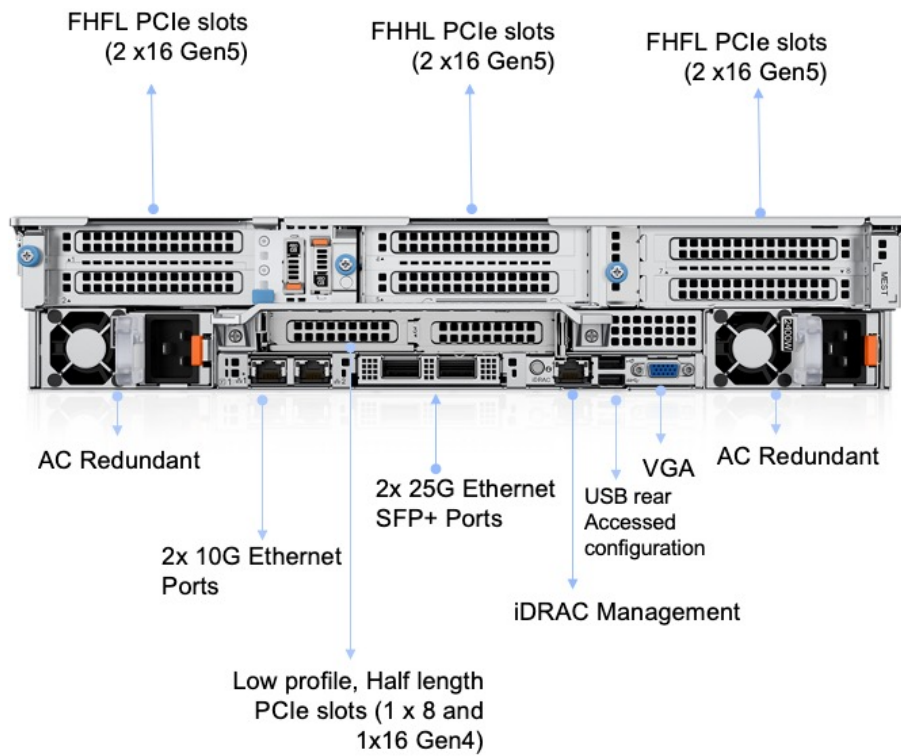
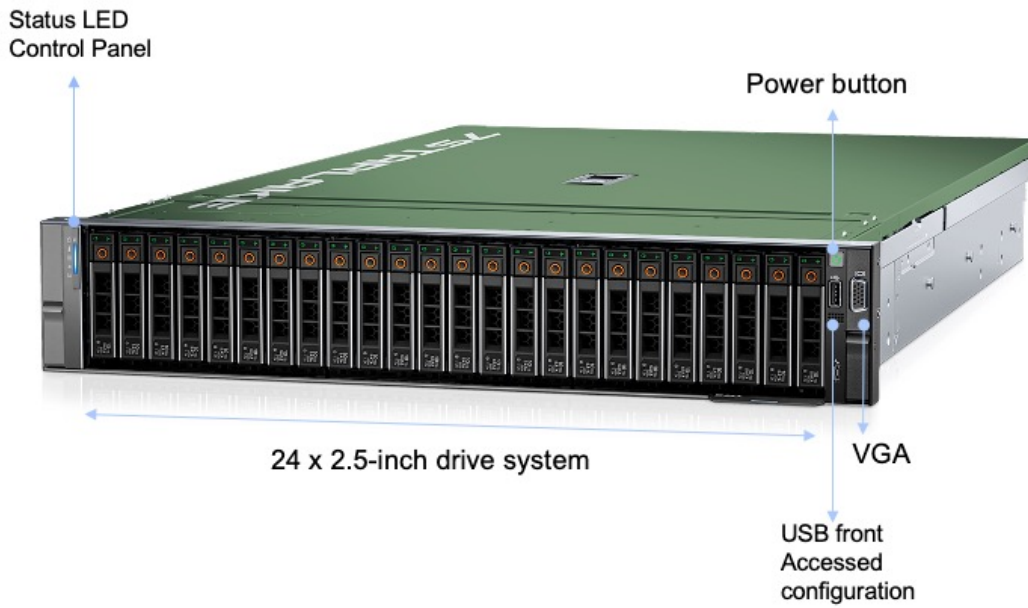
REAR I/O

iDRAC	1x iDRAC dedicated Direct port
USB3.0	1x
Serial	1 x (Micro-AB USB 2.0)
10G LAN	2x
25G LAN	2x
Display port	1x Mini-DP or VGA

ENVIRONMENTAL

MIL-STD-810 Test	Method 500.5, Procedures I and II (Altitude, Operation): 12,192M, (40,000 ft) for the initial cabin altitude (18.8Kpa or 2.73 Psia) Method 500.5, Procedures III and IV (Altitude, Non-Operation): 15,240, (50,000 ft) for the initial cabin altitude (14.9Kpa or 2.16 Psia) Method 501.5, Procedure I (Storage/High Temperature) Method 501.5, Procedure II (Operation/High Temperature) Method 502.5, Procedure I (Storage/Low Temperature) Method 502.5, Procedure II (Operation/Low Temperature) Method 503.5, Procedure I (Temperature shock) Method 507.5, Procedure II (Temperature & Humidity) Method 509.7 Salt Spray (50±5)g/L(Optional for Conformal Coating) Method 514.6, Vibration Category 24/Non-Operating (Category 20 & 24,Vibration) Method 514.6, Vibration Category 20/Operating (Category 20 & 24,Vibration) Method 516.6, Shock-Procedure V Non-Operating (Mechanical Shock) Method 516.6, Shock-Procedure I Operating (Mechanical Shock)
Operating Temp	-10°C to +55°C
Storage Temp.	-20°C to +60°C
Relative Humidity	5% to 95%, non-condensing.

Appearance



Ordering Information

	7SL-R760-AC	7SL-R760-DC
CPU	Two 5th Gen Intel® Xeon® / 4th Gen Intel® Xeon® Scalable processors, Socket E (LGA-4677)	Two 5th Gen Intel® Xeon® / 4th Gen Intel® Xeon® Scalable processors, Socket E (LGA-4677)
RAM	DDR5-5600MT/s RDIMM ECC, up to 8TB in 32 DIMM slot	DDR5-5600MT/s RDIMM ECC, up to 81TB in 32 DIMM slot
Storage	24x 2.5" Swappable SATA SAS, or NVMe (HDD/SSD)	24x 2.5" Swappable SATA SAS, or NVMe (HDD/SSD)
Power	2400W 100V~240V AC IN Redundant	1100W DC 48V~60V
Thermal	Active Smart Fan Cooling	Active Smart Fan Cooling